

METHOD AND SYSTEM FOR PRODUCING RESILIENT SOLDER JOINTS

ABSTRACT OF THE DISCLOSURE

A method includes mounting an electronic component to a circuit board. Solder paste is applied to a board pad of the circuit board and a terminal pad of an electrical component is aligned with the board pad. The terminal includes a pad feature and a pad base. The solder paste is liquefied to cause the solder paste to flow along the pad feature. Then the solder paste is cooled to form a solder joint. The solder joint bonds the board pad and the pad base and forms a connection between the circuit board and the electrical component. Because this solder joint is subject to reduced stress at interface junctures of the solder joint, the solder joint is more resilient than conventional solder joints.